## RENESAS

### D2-IPS Audio SOC

Digital Audio Amplifier Power Stage

The D2-IPS family (D2-24044) device is a high performance, integrated Class-D amplifier power stage. The four power stage outputs are configurable as four separate Half-Bridge outputs, as two Full-Bridge outputs, or combinations of Half-Bridge and Full-Bridge. Individual power stage overload monitoring, on-chip temperature monitoring, and common alert logic outputs provide protection to integrate with the final system's controller.

### **Related Literature**

For a full list of related documents, visit our website:

• D2-24044 device page

### Features

- All digital class-D power stage
- Four configurable power stage outputs supporting:
  - 2 Channels, Bridged
  - 4 Channels, Half-Bridge
  - 2 Channels, Half-Bridge, plus 1 Channel, Bridged
- Output Power (bridged)
  - 25W (8Ω, <1% THD)
  - 30W (8Ω, <10% THD)
- Single HV supply wide 9V-26V range, plus internally-generated gate drive supply
- Individual channel protection monitoring
- Temperature and undervoltage monitoring
- Efficient 38 Ld HTSSOP package

### Applications

- PC/multimedia speakers
- Digital TV audio systems
- Portable device docking stations
- Powered speaker systems

### **Digital Amplifier Power Stage**



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### **Ordering Information**

PART NUMBER PART ( <u>Note 3</u> ) MARKING		APPLICATION SUPPORT	TEMP. RANGE (°C)	TAPE AND REEL (UNITS) ( <u>Note 1</u> )	PACKAGE (Pb-Free)	PKG. DWG. #	
D2-24044-MR	D2-24044-MR	Commercial	-10 to +85	-	38 Ld HTSSOP	M38.173C	
D2-24044-MR-T	D2-24044-MR	Commercial	-10 to +85	2.5k	38 Ld HTSSOP	M38.173C	

NOTES:

1. See <u>TB347</u> for details about reel specifications.

2. These Pb-free plastic packaged products employ special Pb-free material sets, molding compounds/die attach materials, and 100% matte tin plate plus anneal (e3 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations). The Pb-free products are MSL classified at Pb-free peak reflow temperatures that meet or exceed the Pb-free requirements of IPC/JEDEC J STD-020.

3. For Moisture Sensitivity Level (MSL), see the <u>D2-24044</u> device page. For more information about MSL, see <u>TB363</u>.



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#### **Absolute Maximum Ratings**

Supply Voltage	
HVDD[A:D], VDDHV	0V to +28.0V
PWMVDD	0V to 4.0V
Input Voltage	
Any Input	MVDD + 0.3V

#### **Thermal Information**

Thermal Resistance (Typical)	$\theta_{JA}$ (°C/W)	θ <sub>JC</sub> (°C/W)
38 Ld HTSSOP Package (Notes 4, 5	) 29	1.3
Maximum Storage Temperature	55°	C to +150°C
Pb-Free Reflow Profile		. see <u>TB493</u>

#### **Recommended Operating Conditions**

Temperature Range	10°C to +85°C
High Voltage Supply Voltage,	
HVDD[A:D], VDDHV	
Digital I/O Supply Voltage, PWMVDD	
Minimum Load Impedance (HVDD[A:D] ≤24.0	V), Z <sub>L</sub> 4Ω

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions can adversely impact product reliability and result in failures not covered by warranty.

NOTES:

- 4.  $\theta_{JA}$  is measured in free air with the component mounted on a high-effective thermal conductivity test board with "direct attach" features. See <u>TB379</u>.
- 5. For  $\theta_{1C}$ , the "case temp" location is the center of the exposed metal pad on the package underside.
- 6. Absolute Maximum parameters are not tested in production.

#### **Electrical Specifications**

TA = +25°C, PWMVDD = 3.3V ±10%. All grounds at 0.0V. All voltages referenced to ground.

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	түр	МАХ	UNIT
Digital Input High Logic Level		$V_{IH}$	2	-	-	V
Digital Input Low Logic Level		V <sub>IL</sub>	-	-	0.4	V
High Level Output Drive Voltage (I <sub>OUT</sub> at -Pin Drive Strength Current)		V <sub>OH</sub>	PWMVDD-0.4	-	-	V
Low Level Output Drive Voltage (I <sub>OUT</sub> at +Pin Drive Strength Current)		V <sub>OL</sub>	-	-	0.4	V
Input Leakage Current	Pins 1, 2, 3	I <sub>IN</sub>	-	-	±10	μA
	PWM Input Pins (includes $100k\Omega$ internal pull-down resistor current)	-	-	-	±50	μA
Input Capacitance		C <sub>IN</sub>	-	9	-	pF
Output Capacitance	All Outputs Except OUT[A:D]	C <sub>OUT</sub>	-	9	-	pF
	OUT[A:D]		-	190	-	
Internal Pull-Up Resistance to PWMVDD (for nERRORA-D, nOVRT)			-	100	-	kΩ
Digital I/O Supply Pin Voltage, Current		PWMVDD	3	3.3	3.6	V
	Active Current		-	0.47	-	mA
	Power-Down Current		-	0.15	-	mA
3.3V (PWMVDD) BROWN-OUT DETECTION						
Logic Supply Undervoltage Threshold			-	2.6	-	V
Logic Supply Undervoltage Threshold Hysteresis			-	200	-	mV
Logic Supply Undervoltage Glitch Rejection			-	50	-	ns



#### **Electrical Specifications**

TA = +25°C, PWMVDD = 3.3V ±10%. All grounds at 0.0V. All voltages referenced to ground.

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	түр	МАХ	UNIT
GATE DRIVE INTERNAL +5V BROWN-OUT D	ETECTION				•	
Gate Drive Supply Undervoltage Threshold			-	4.5	-	V
Gate Drive Supply Undervoltage Threshold Hysteresis			-	200	-	mV
Gate Drive Supply Undervoltage Threshold Glitch Rejection			-	50	-	ns
PROTECTION DETECT						
High Voltage Undervoltage Protection			-	7	9	V
Overcurrent Trip Threshold			-	4	-	А
Overcurrent De-glitch			-	2.5	-	ns
Short-Circuit Current Limit (Peak)			-	8	-	А
Overcurrent Response Time			-	20	-	ns
Thermal Shut-Down OTmax			-	140	-	°C
Thermal Warning Temperature OTmin			-	125	-	°C
Thermal Shut-Down Hysteresis			-	30	-	°C
Thermal Warning Hysteresis			-	20	-	°C

#### **Performance Specifications**

 $T_A$  = +25°C, PWMVDD = 3.3V ±10%. All grounds at 0.0V. All voltages referenced to ground.

PARAMETER	SYMBOL	MIN	ТҮР	МАХ	UNIT
r <sub>DS(ON)</sub> (MOSFETs @ +25°C)	r <sub>DS(ON)</sub>	-	200	-	mΩ
r <sub>DS(ON)</sub> Mismatch		-	1	-	%
PWM Switching Rate		-	384	-	kHz
Minimum PWM Pulse Width		-	3.5	-	ns
PWM Off Sensor Time		-	10	-	μs
PWM Input to Output Delay		-		50	ns
PWM Input to Output Delay Matching		-	3	-	ns
nPDN Input Off Delay	T <sub>PDNOFF</sub>	-	1.4	-	ms
nPDN Input On Delay	T <sub>PDNON</sub>	-	1.4	-	ms
POWER OUTPUT					
<1% THD, Bridged, Load = $8\Omega$ , HVDD[A:D] = 24V	POUT	-	25	-	W
<10% THD, Bridged, Load = $8\Omega$ , HVDD[A:D] = 24V	POUT	-	30	-	W
<1% THD, Half-Bridge, Load = $8\Omega$ , HVDD[A:D] = 24V	POUT	-	7	-	W
<10% THD, Half-Bridge, Load = $8\Omega$ , HVDD[A:D] = 24V	POUT	-	9	-	W
THD+N		-			
Load = $8\Omega$ , Power = 25W, Bridged, 1kHz	THD+N	-	0.3	-	%
Load = $8\Omega$ , Power = 1W, Bridged, 1kHz		-	0.05	-	%
SNR	SNR	-	110	-	dB
Efficiency (Load = $8\Omega$ )		-	90	-	%



### **Pin Configuration**



### **Pin Description**

PIN	PIN NAME ( <u>Note 7</u> )	ТҮРЕ	VOLTAGE LEVEL (V)	DESCRIPTION
1	nPDN	I	3.3	Power-down and mute input. Active low. When this input is low, all four outputs become inactive, their output stages float, and their output is muted. Internal logic and other references remain active during this power-down state.
2	OCFG1	Ι	3.3	Output configuration control select. OCFG0 and OCFG1 are logic inputs to select the
3	OCFG0	Ι	3.3	output configuration mode of the output stages. Connects to either PWMGND ground or PWMVDD (+3.3V) through a nominal $10k\Omega$ resistor to select the output configuration.
4	PWMGND	GND	0	Low-voltage ground. Connects to ground of circuitry providing PWM inputs. Both PWMGND and PWMGND2 must be tied together to the same ground.
5	PWMVDD	Р	3.3	Low-voltage power. This 3.3V supply connects to the same system low-voltage power used for providing PWM inputs.
6	nOVRT	0	3.3	Over-temperature warning output. Open drain, 16mA drive strength output with pull-up. Pulls low when active from over-temperature detection.
7	PWM1	Ι	3.3	PWM Input. Routes to output channel, dependent on output configuration settings.
8	PWM2	Ι	3.3	
9	PWM3	Ι	3.3	
10	PWM4	Ι	3.3	
11	PWM5	Ι	3.3	
12	PWM6	Ι	3.3	
13	PWM7	Ι	3.3	
14	PWM8	Ι	3.3	



### Pin Description (Continued)

PIN	PIN NAME ( <u>Note 7</u> )	ТҮРЕ	VOLTAGE LEVEL (V)	DESCRIPTION			
15	PWMGND2	GND	0	Low-voltage ground. Connects to ground of circuitry providing PWM inputs. Both PWMGND and PWMGND2 must be tied together to the same ground.			
16	nERRORA	0	3.3	Overcurrent protection output, channel A output stage. Open drain, 16mA drive strength output with pull-up. Pulls low when active from overcurrent detection of output stage.			
17	nERRORB	0	3.3	Overcurrent protection output, channel B output stage. Open drain, 16mA drive strength output with pull-up. Pulls low when active from overcurrent detection of output stage.			
18	nERRORC	0	3.3	ercurrent protection output, channel C output stage. Open drain, 16mA drive streng tput with pull-up. Pulls low when active from overcurrent detection of output stage			
19	nERRORD	0	3.3	Overcurrent protection output, channel D output stage. Open drain, 16mA drive strength output with pull-up. Pulls low when active from overcurrent detection of output stage.			
20	HVDDD	Р	HV	Output stage D high voltage supply power. A separate power pin connection is provided for each of the output stages. All of the HVDD[A:D] pins and the VDDHV pin connect to the system "HV" power source.			
21	HGNDD	GND	HV	Output stage D high voltage supply ground. A separate ground pin connection is provided for each of the output stages. All of the HGND[A:D] pins connect to the system "HV" power ground (also see Note 8).			
22	OUTD	0	HV	PWM power amplifier output, channel D.			
23	HSBSD	Ι	HV	High side boot strap input, output channel D. Capacitor couples to the OUTD amplifier output.			
24	HSBSC	Ι	HV	High side boot strap input, output channel C. Capacitor couples to the OUTC amplifier output.			
25	OUTC	0	HV	PWM power amplifier output, channel C.			
26	HGNDC	GND	HV	Output stage C high voltage supply ground. A separate ground pin connection is provided for each of the output stages. All of the HGND[A:D] pins connect to system "HV" power ground (also see <u>Note 8</u> ).			
27	HVDDC	Р	HV	Output stage C high voltage supply power. A separate power pin connection is provided for each of the output stages. All of the HVDD[A:D] pins and the VDDHV pin connect to the system "HV" power source.			
28	IREF	I	-	Overcurrent reference analog input used to set the overcurrent error to detect externally- set threshold. The pin needs to be connected to a $100k\Omega$ resistor to ground to set the overcurrent threshold according to the specified limits.			
29	VDDHV	Р	+HV	High Voltage internal driver supply power. All of the HVDD[A:D] pins and the VDDHV pin connect to the system "HV" power source. The internal +5V supply regulators also operate from this VDDHV input.			
30	REG5V	Р	5	5V internal regulator filter connect. A +5V supply is internally generated from the voltage source provided at the VDDHV pin. REG5V is used for external connection of a decoupling capacitor.			
31	HVDDB	Р	HV	Output stage B high voltage supply power. A separate power pin connection is provided for each of the output stages. All of the HVDD[A:D] pins and the VDDHV pin connect to the system "HV" power source.			
32	HGNDB	GND	HV	Output stage B high voltage supply ground. A separate ground pin connection is provided for each of the output stages. All of the HGND[A:D] pins connect to the system "HV" power ground (also see <u>Note 8</u> ).			
33	OUTB	0	HV	PWM power amplifier output, channel B.			
34	HSBSB	Ι	HV	High side boot strap input, output channel B. Capacitor couples to the OUTB amplifier output.			
35	HSBSA	Ι	HV	High side boot strap input, output channel A. Capacitor couples to the OUTA amplifier output.			



### Pin Description (Continued)

		-		
PIN	PIN NAME ( <u>Note 7</u> )	ТҮРЕ	VOLTAGE LEVEL (V)	DESCRIPTION
36	OUTA	0	HV	PWM power amplifier output, channel A.
37	HGNDA	GND	ΗV	Output stage A high voltage supply ground. A separate ground pin connection is provided for each of the output stages. All of the HGND[A:D] pins connect to the system "HV" power ground (also see <u>Note 8</u> ).
38	HVDDA	Р	ΗV	Output stage A high voltage supply power. A separate power pin connection is provided for each of the output stages. All of the HVDD[A:D] pins and the VDDHV pin connect to the system "HV" power source.

NOTES:

- 7. Unless otherwise specified all pin names are active high. Those that are active low have an "n" prefix, such as nERRORA.
- 8. Thermal pad is internally connected to all 4 HGND ground pins (HGNDA, HGNDB, HGNDC, HGNDD). Any connection to the thermal pad must be made to the common ground for these 4 ground pins.

### **Typical Performance Characteristics**



FIGURE 1. THD vs POWER, FULL-BRIDGE



FIGURE 2. THD vs FREQUENCY, FULL-BRIDGE

















FIGURE 7. FREQUENCY RESPONSE, HALF-BRIDGE



FIGURE 8. NOISE FLOOR, HALF-BRIDGE



### **Functional Overview**

The devices include four independent output stages (Figure 9) that are each implemented using a high side (to the positive VDDHV supply) and a low side (to the HV supply ground) FET pair. Drivers and overcurrent monitoring are included in each of these four output stages. Depending on the selected configuration mode, these four stages can be used independently as single half-bridge outputs, or as pairs for full-bridge outputs.

Digital PWM inputs are connected to the PWM input pins, where their signals are routed through the configuration select logic to the individual output FETs and drivers.

On-chip temperature and undervoltage monitoring, and individual per-output current monitoring provides protection and status reporting outputs to the system controller.

Upon application of power, the on-chip voltage sensors monitor presence of the required power voltages. Until all voltages are at their design specifications, the outputs remain off and floating.

After supply voltages are within limits and stable, the output configuration is set by the logic levels at the OCFG0 and OCFG1 input pins, and the PWM inputs are routed to their appropriate output stage FETs.



FIGURE 9. OUTPUT STAGE

### **Output Options**

The D2-IPS family devices provide four configuration options for the outputs. These options are selected by strapping the OCFG0 and OCFG1 pins high or low. These defined configurations include:

- 2 Channels of Full Bridge, 4-Quadrant Outputs
- 2 Channels of Full Bridge, 2-Quadrant Outputs
- 4 Channels of Half-Bridge Outputs
- 2 Channels Half-Bridge, Plus 1 Channel Full Bridge

When a configuration is set that includes a full-bridge output, each input channel's PWM input signal is routed to the high and low side FETs, appropriate for that full bridge operation. Note however, that the device can be configured as four independent half-bridge outputs (using mode "11" as described in the configuration assignment table on <u>page 14</u>) and two of those outputs can be used in a full bridge configuration, by connecting the appropriate PWM input pins to the input source. This configuration allows flexibility in applications that require combinations other than the four defined by the output configuration modes.

### **Power Supply Requirements**

The device operates from two supply voltages:

- PWMVDD is a nominal 3.3V supply voltage and operates the logic and control.
- HVDD (HVDD[A:D], and VDDHV) is the "high voltage" used for operating the output power stages.

Individual HVDD and its ground (HGND) pins are included for each of the four power stage outputs, providing channel isolation and low impedance source connections to each of the outputs. A separate VDDHV pin is used for the output drivers, and is the source for the on-chip regulated 5V source needed for the drivers. All the HVDD/VDDHV pins connect to the same voltage source.

PWMVDD is the reference for the PWM inputs and device control logic, and is the same voltage as used by the PWM/system controller.

#### High Side Gate Drive Voltage

An on-chip bootstrap circuit provides the high-side gate drive voltage used by each output stage. A pin is included for each output channel (HSBS[A:D]) for connection of a capacitor (nominal,  $0.22\mu$ F/50V) from this pin to that channel's PWM output. The charge pumping actions uses this capacitor to filter and hold this gate drive voltage, and enables amplifier operation without need of connection to an additional power supply voltage.

#### **Supply Bypass Connection**

Connect power supply bypass capacitors across each of the power supply connection pins, as follows:

- Four HVDD power pins and their respective HGND ground pins. These should be a parallel combination of a nominal  $100\mu F$  and  $0.1\mu F$  capacitors, located as close as possible to the HVDD/HGND pin pair.
- Connect a  $0.1 \mu \text{F}$  capacitor at the VDDHV pin.
- The PWMVDD power pin should include a  $1\mu\text{F}$  and  $0.1\mu\text{F}$  capacitor.

#### REG5V

The on-chip gate drive power supply operates from the VDDHV power input to produce the 5V supply voltage. The REG5V pin is used for external capacitor connection to filter this regulated voltage. A  $1.0\mu$ F and  $0.1\mu$ F capacitor should be connected to this pin, and the connection should be made as close as practical to the pin. Do not make any other connections to be made to this pin.



### **Input and Control Functions**

#### **PWM Inputs**

Eight PWM input pins provide the PWM inputs to the amplifier's output stages. The PWM input pins are electrically single-ended and are referenced to the PWMVDD and PWMGND supplies.

PWM drive to the output stages is provided differentially on-chip, with the PWM input channels mapped to each of the high-side output FETs and the low-side output FETs that implement the individual power stages. Routing and assignment of the PWM input pins to the output FETS is defined by the configuration mode. Figures <u>11</u>, <u>12</u>, <u>13</u>, and <u>14</u> show the mapping of these input pins to the outputs for each of the four configuration modes.

All eight input pins however are not always used in each of the configuration modes. For example, in mode "00", providing 3-level drive of two channels of full bridge outputs, or in mode "11" providing four independent half-bridge outputs, one PWM input is dedicated to each of the FETs. But in mode "01" that implements two 2-quadrant full-bridge outputs, only four PWM inputs are used, and the logical high/low states are routed to the FETs as needed.

#### **nPDN Input Pin**

The nPDN pin is a control input that is used to set the inactive (powered down) state, and also mute the outputs. It operates by turning off drive and internal sources to the PWM outputs, as well as turning off the PWM drive to those outputs.

When an overcurrent condition is detected on an output, causing its overcurrent protection to latch and turn off that output, asserting the nPDN input resets the device and clears this overcurrent state.

The nPDN pin is active low, and inactive when at logic high level.

#### **nERRORA-D** Output Pins

Each of the four outputs includes an overload and overcurrent monitor. An overcurrent or overload condition asserts the nERROR output for that channel. These outputs are active low and open drain. Depending on the output mode configuration and need to monitor more than one output, these nERROR pins can be wire-or connected together.

#### **nOVRT Output Pin**

The nOVRT pin is an output that provides warning of a high temperature condition. It is an open drain, active low output. This pin only provides an indication for the high-temperature condition.

#### **IREF** Pin

The IREF pin is used to control the overcurrent monitoring threshold. A  $100 {\rm k}\Omega$  resistor connects from this pin to ground.

#### **OCFG0, OCFG1 Input Pins**

These two pins are used to define the configuration of the four output stages. They are connected to logic high (PWMVDD) or logic ground (PWMGND) to set their level. See <u>"Output Mode Configurations" on page 14</u> for additional reference and definition.

### Protection

The D2-IPS family device includes monitors for protection of the system as well as the device itself. Certain levels of protection are managed on-chip, as shown in Figure 10. Other protection is integrated at the system level through the system controller, and involves system design decisions based on:

- A short-circuit, over-temperature, or undervoltage event shuts down the outputs.
- Other operation depends on the PWM/system controller to properly manage full system protection operation.
- Power supply sensors shut down the device if supply voltages drop below their design thresholds.
- Overload and overcurrent monitors provide dual threshold status of high current conditions, providing both indication, and device shutdown if needed.
- Chip temperature monitoring provides dual threshold status of high temperature conditions, providing both indication, and device shutdown if needed.

#### Short-Circuit and Overcurrent Sensing

Each PWM output FET includes a dual-threshold overcurrent sensor. Multiple functions occur depending on detection of overcurrent conditions:

- The lower threshold is used to monitor fault conditions after the output stage filter inductor, such as shorts or overloads on the loudspeaker outputs.
- The higher threshold monitors fault conditions of the PWM output pin.
- The nERROR output asserts for the channel detecting the fault.
- For the lower level threshold, nERROR remains asserted only through the duration of the overcurrent event.
- For the higher level threshold, the output is shut down and its nERROR output is asserted. These outputs remain latched until the controller acknowledges the fault event by turning off the channel's PWM drive. (When the output is shutdown, its PWM output pin floats.)



#### **Thermal Protection and Monitoring**

An on-chip temperature sensor provides two temperature monitoring thresholds.

If the device reaches the lower threshold, the nOVRT output is asserted and provides a warning indication to an external controller. The low threshold setting provides indication only and does not have any effect on device operation.

• The lower high-temperature threshold (warning) is set at approximately +125°C.

If the device reaches the higher threshold, it drives all four nERRORA-D outputs low (active) and shuts down the device, in addition to asserting the nOVRT output. This shutdown in non-latching, and operation resumes automatically when temperature returns to normal.

• The higher high-temperature threshold (overtemperature) is set at approximately +140°C.

#### **Power Supply Voltage Monitoring**

Undervoltage monitors are included for the output drive (HVDD) supply voltage, the on-chip generated gate drive (REG5V) supply voltage, and the low-level PWMVDD supply voltage. Detection occurs at approximately 2.5V for PWMVDD, approximately 4V for the gate drive supply, and approximately 7V for the HVDD supply. (Limits are listed in the electrical specification tables starting on page 4.)

If any of the monitored voltages drop below their thresholds, the device shuts down its outputs and asserts all four of the nERROR outputs. Operation resumes normally after the undervoltage condition is cleared.



Overcurrent (OC) Shutdown: OC detect condition is latched, shutting down output. Latched shutdown is then cleared after overcurrent condition has cleared, AND PWM data clocking has stopped from PWM controller.



### **Output Mode Configurations**

The D2-IPS family device supports four amplifier output configuration modes, utilizing the device's four power stage outputs.

Configuration selection is controlled by the OCFG0 and OCFG1 pins by connecting them to either a high (+3.3V, PWMVDD = 1) or low (ground = 0) level. Settings are chosen based on the output configuration and topology of the design. Their connections must be hard-connected on the design, and they must be dynamic or subject to change during system operation.

For each of the four configurations, the PWM input pin signals route to the individual FETs of each of the power stages to implement the channel drive and topology needed for those configurations. Figures 11, 12, 13, and 14 show this routing of the PWM inputs to each of the power stages, and how the particular topology is implemented for that configuration. Table 1 shows the configuration functions that are defined with the combinations of the OCFG pins, and these diagrams show the implementation that is listed in this table.

CONFIG PINS			CONFIGURATION	POWER STAGE OUTPUT				nERROR CHANNEL USE				
OCFG1	OCFG0	CONFIG	DESCRIPTION	OUTA	OUTB	Ουτς	OUTD	nERRORA	nERRORB	nERRORC	nERRORD	
			2-Channel	Out Chan	put nel 1	Out Chan	tput Inel 2	Connect	(wire-or) & nERRORB	Connect (wire-or) nERRORC & nERRORD		
			Full Bridge 3-Level	High-Sid	e FET PWM	Input Assi	ignments	Use for	output	Use for	output	
0	0	"00″	PWM Drive	PWM1	PWM3	PWM5	PWM7	Channel	1 Protect	Channel	2 Protect	
			( <u>Figure 11</u> )	Low-Side	e FET PWM	Input Assi	gnments	-				
			, , , , , , , , , , , , , , , , , , , ,	PWM2	PWM4	PWM6	PWM8	-				
			2-Channel	Out Chan	put nel 1	Out Chan	tput Inel 2	Connect	(wire-or) & nERRORB	Connect (wire-or) nERRORC & nERRORD		
			Full Bridge,	High-Sid	e FET PWM	Input Assi	ignments	toge Use for	ther. Output	toge Use for	ther. Output	
0	0 1 "01"		01" 2-Quadrant PWM Drive	PWM1	PWM2	PWM3	PWM4	Channel	1 Protect	Protect Channel 2		
			(Figure 12)	Low-Side FET PWM Input Assignr		gnments						
				PWM2	PWM1	PWM4	PWM3					
			2-Channel	Output Ch. 1	Output Ch 2	Out Chan	tput Inel 3			Connact (wire or)		
			plus	High-Sid	e FET PWM	Input Assi	ignments	nERRORA	nERRORB	nERRORC &	k nERRORD	
1	0	"10"	1-Channel Full Bridge	PWM1	PWM3	PWM5	PWM6	Channel 1	Channel 2	toge Use for	ther. Output	
					Low-Side FET PWM Input Assignments			Protect	Protect	Channel	3 Protect	
			( <u>Figure 13</u> )	PWM2	PWM4	PWM6	PWM5	-				
				Output Ch. 1	Output Ch 2	Output Ch. 3	Output Ch 4					
			4-Channel Half-Bridge	High-Sid	High-Side FET PWM Input Assignments			, nERRORA	nERRORB	nERRORC	nERRORD	
1	1	"11″	(Figure 14)	PWM1	PWM3	PWM5	PWM7	Channel 1	Channel 2	Channel 3	Channel 4	
				Low-Side	e FET PWM	Input Assi	gnments	Protect	Protect	Protect	Protect	
				PWM2	PWM4	PWM6	PWM8					

#### TABLE 1. D2-IPS FAMILY CONFIGURATION PWM AND OUTPUT CHANNEL ASSIGNMENTS



FIGURE 11. CONFIGURATION "00" PWM INPUT-TO-OUTPUT POWER STAGE MAPPING



FIGURE 12. CONFIGURATION "01" PWM INPUT-TO-OUTPUT POWER STAGE MAPPING



FIGURE 13. CONFIGURATION "10" PWM INPUT-TO-OUTPUT POWER STAGE MAPPING



FIGURE 14. CONFIGURATION "11" PWM INPUT-TO-OUTPUT POWER STAGE MAPPING

### **Typical Application Examples**

These examples show functional circuit examples of typical applications using the D2-IPS family device. (Note: These examples are provided to show typical applications only and are not intended to represent complete production-qualified reference designs.)

#### 2-Channel Full Bridge Example

This example (Figure 15) uses configuration mode "01'' to provide two full-bridge loudspeaker output channels. The PWM controller provides input into four PWM input pins.



FIGURE 15. 2-CHANNEL FULL BRIDGE EXAMPLE



#### 2.1-Channel Example

This example (Figure 16) uses configuration mode "10" to provide two independent half-bridge loudspeaker output channels, plus one full-bridge loudspeaker output. The PWM controller provides input into all eight PWM input pins.



FIGURE 16. 2-CHANNEL HALF BRIDGE PLUS 1-CHANNEL FULL BRIDGE EXAMPLE



#### 4-Channel Half-Bridge Example

This example (Figure 17) uses configuration mode "11" to provide four independent half-bridge loudspeaker output channels. The PWM controller provides input into all eight PWM input pins.



FIGURE 17. 4-CHANNEL HALF BRIDGE EXAMPLE



# **Revision History** The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Visit our website to make sure you have the latest datasheet revision.

DATE	REVISION	CHANGE
Mar 18, 2019	FN7678.1	Updated title to "D2-IPS Audio SOC". Updated "D2-24044" to "D2 IPS Family". Removed About Intersil section. Updated disclaimer.
Sep 3, 2010	FN7678.0	Initial Release



### Package Outline Drawing

For the most recent package outline drawing, see M38.173C.

#### M38.173C

38 LEAD HEAT-SINK THIN SHRINK SMALL OUTLINE PLASTIC PACKAGE (HTSSOP) Rev 0, 4/10



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